## **STARPOWER**

SEMICONDUCTOR™

# **IGBT**

## **GD400HFU120C2S**

**Molding Type Module** 

1200V/400A 2 in one-package

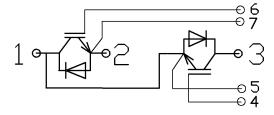
### **General Description**

STARPOWER IGBT Power Module provides ultrafast switching speed as well as short circuit ruggedness. It's designed for the applications such as electronic welder and Inductive heating.



#### **Features**

- 10µs short circuit capability
- Low switching losses
- Rugged with ultrafast performance
- V<sub>CE(sat)</sub> with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



**Equivalent Circuit Schematic** 

### **Typical Applications**

- Switching mode power supplies
- Inductive heating
- Electronic welder

# Absolute Maximum Ratings $T_C=25$ °C unless otherwise noted

Symbol	Description	GD400HFU120C2S	Units
V <sub>CES</sub>	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	±20	V
T	Collector Current @ T <sub>C</sub> =25°C	660	Α.
$I_{\rm C}$	@ T <sub>C</sub> =80°C	400	A
I <sub>CM(1)</sub>	Pulsed Collector Current t <sub>p</sub> =1ms	800	A
$I_{F}$	Diode Continuous Forward Current	400	A
$I_{FM(1)}$	Diode Maximum Forward Current	800	A
$P_{D}$	Maximum power Dissipation @ T <sub>j</sub> =150°C	2660	W
$T_{SC}$	Short Circuit Withstand Time @ $T_j=125^{\circ}C$	10	μs
$T_{\rm j}$	Maximum Junction Temperature	150	$^{\circ}\!\mathbb{C}$
$T_{STG}$	Storage Temperature Range	-40 to +125	$^{\circ}\!\mathbb{C}$
$V_{\rm ISO}$	Isolation Voltage RMS,f=50Hz,t=1min	2500	V
Mounting Torque	Power Terminal Screw:M6	2.5 to 5.0	N.m
	Mounting Screw:M6	3.0 to 6.0	N.m

#### **Notes:**

# Electrical Characteristics of IGBT $_{\text{T}_{\text{C}}\!=\!25\,^{\circ}\!\text{C}}$ unless otherwise noted

#### **Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V <sub>(BR)CES</sub>	Collector-Emitter	$T_i=25$ °C	1200			V
	Breakdown Voltage	1j=25 C				•
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0V,$			5.0	A
		T <sub>j</sub> =25℃				mA
$I_{GES}$	Gate-Emitter Leakage	$V_{GE}=V_{GES}, V_{CE}=0V,$			400	nA
	Current	T <sub>j</sub> =25℃			400	

#### **On Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
$V_{\text{GE(th)}}$	Gate-Emitter Threshold	$I_{C}=4.0\text{mA}, V_{CE}=V_{GE},$	4.4	4.9	6.0	V
	Voltage	$T_j=25^{\circ}C$	4.4			
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	$I_{C}$ =400A, $V_{GE}$ =15V,		3.10	3.60	
		$T_j=25$ °C				17
		$I_{C}$ =400A, $V_{GE}$ =15V,		3.45		v
		T <sub>j</sub> =125℃				

<sup>(1)</sup> Repetitive rating: Pulse width limited by max. junction temperature

## **Switching Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
t <sub>d(on)</sub>	Turn-On Delay Time			680		ns
t <sub>r</sub>	Rise Time			142		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V (00VI 400A		638		ns
$t_{\rm f}$	Fall Time	V <sub>CC</sub> =600V,I <sub>C</sub> =400A,		99		ns
E <sub>on</sub>	Turn-On Switching Loss	$R_{G}=2.2\Omega, V_{GE}=\pm 15 V,$ $T_{j}=25 ^{\circ}C$		19.0		mJ
$E_{\rm off}$	Turn-Off Switching Loss	1		32.5		mJ
t <sub>d(on)</sub>	Turn-On Delay Time			690		ns
t <sub>r</sub>	Rise Time			146		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V (00VI 400A		669		ns
$t_{\rm f}$	Fall Time	$V_{CC}$ =600V, $I_{C}$ =400A, $R_{G}$ =2.2 $\Omega$ , $V_{GE}$ = $\pm$ 15 V, $T_{j}$ =125 °C		108		ns
Eon	Turn-On Switching Loss			26.1		mJ
$E_{\rm off}$	Turn-Off Switching Loss			36.7		mJ
Cies	Input Capacitance			33.7		nF
Coes	Output Capacitance	V <sub>CE</sub> =30V,f=1MHz, V <sub>GE</sub> =0V		2.99		nF
$C_{res}$	Reverse Transfer Capacitance			1.21		nF
$I_{SC}$	SC Data	$T_P \le 10 \mu s, V_{GE} = 15 \text{ V},$ $T_j = 25 ^{\circ}\text{C}, V_{CC} = 600 \text{V},$ $V_{CEM} \le 1200 \text{V}$		2600		A
R <sub>Gint</sub>	Internal Gate Resistance			0.5		Ω
L <sub>CE</sub>	Stray Inductance				18	nН
R <sub>CC'+EE'</sub>	Module Lead Resistance, Terminal To Chip	T <sub>C</sub> =25°C		0.32		mΩ

# **Electrical Characteristics of DIODE** $T_C=25\,^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
$V_{\mathrm{F}}$	Diode Forward	I -400 A	T <sub>j</sub> =25℃		1.95	2.35	V
	Voltage	$I_F = 400A$	T <sub>j</sub> =125℃		1.85		<b>\</b>
$Q_{\rm r}$	December of Change		T <sub>j</sub> =25℃		24.1		μС
	Recovered Charge	I <sub>F</sub> =400A,	T <sub>j</sub> =125℃		44.3		
т	Peak Reverse	$V_{R} = 600  \text{V},$	T <sub>j</sub> =25℃		220		4
$I_{RM}$	Recovery Current	di/dt=-2850A/μs,	T <sub>j</sub> =125℃		295		A
E <sub>rec</sub>	Reverse Recovery	V <sub>GE</sub> =-15V	T <sub>j</sub> =25℃		13.9		I
	Energy		T <sub>j</sub> =125℃		24.8		mJ

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# **Thermal Characteristics**

Symbol	Parameter		Max.	Units
$R_{ heta JC}$	Junction-to-Case (per IGBT)		0.047	K/W
$R_{ heta JC}$	Junction-to-Case (per DIODE)		0.096	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.035		K/W
G	Weight of Module	350		g

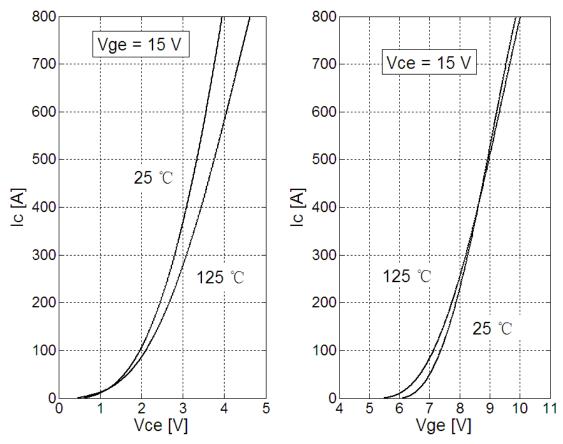


Fig 1. IGBT Typical Output Characteristics Fig 2. IGBT Typical Transfer Characteristics

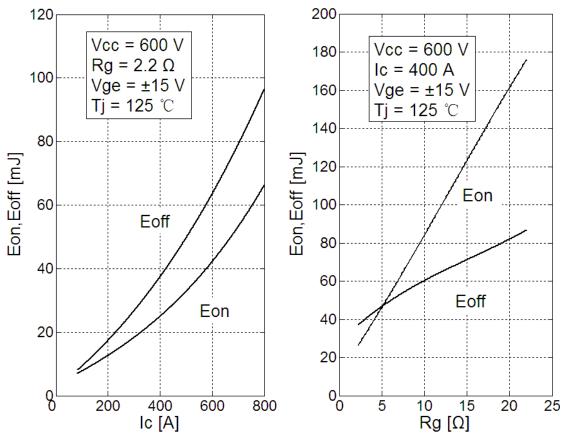


Fig 3. IGBT Switching Loss vs.  $I_{\rm C}$ 

Fig 4. IGBT Switching Loss vs.  $R_{\rm G}$ 

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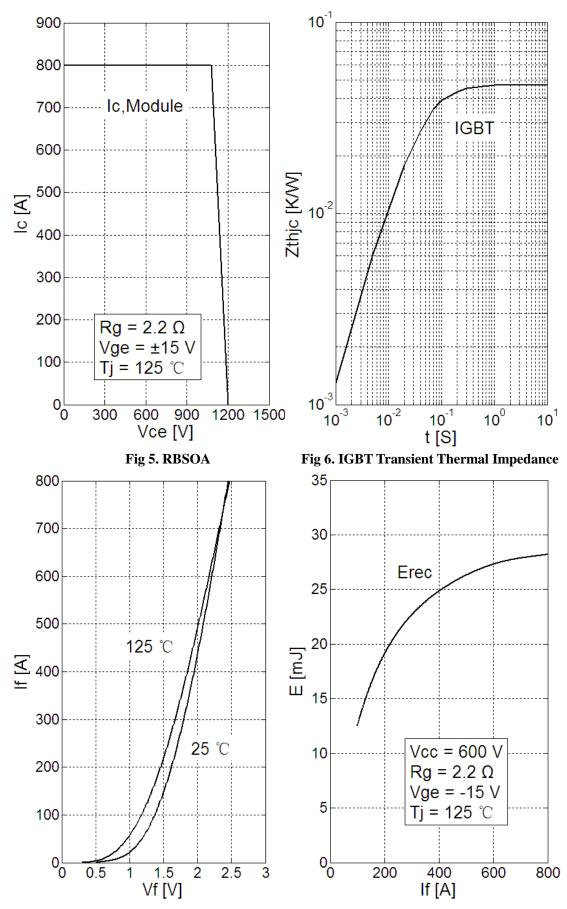


Fig 7. Diode Typical Forward Characteristics

Fig 8. Diode Switching Loss vs.  $I_{\rm F}$ 

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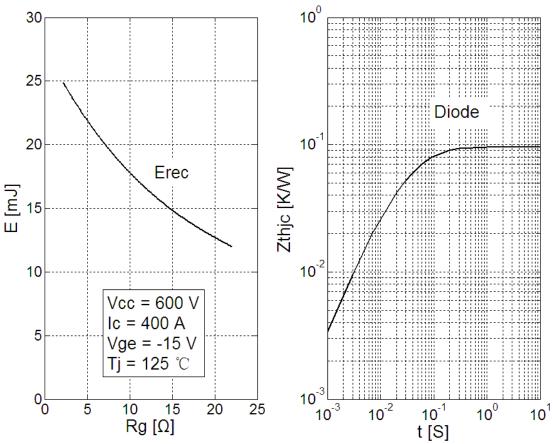
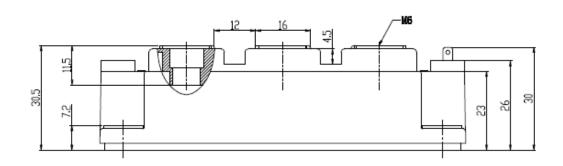


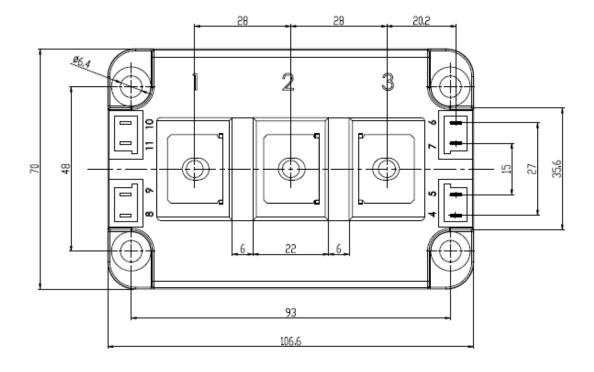
Fig 9. Diode Switching Loss vs.  $R_{\rm G}$ 

Fig 10. Diode Transient Thermal Impedance

# **Package Dimension**

#### **Dimensions in Millimeters**





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